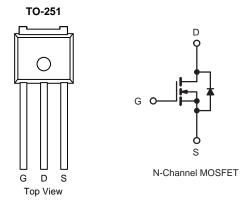


N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$\mathbf{R}_{\mathbf{DS(on)}}$ ($\mathrm{m}\Omega$)	I _D (A)	Q _g (Typ.)		
30	7 at V _{GS} = 10 V	50	19 nC		
	9 at V _{GS} = 4.5 V	45	19110		



FEATURES

- Halogen-free
- TrenchFET[®] Gen III Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- DC/DC Conversion
 - System Power



COMPLIANT

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		50		
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	I _D	45		
	T _A = 25 °C	טי	14 ^{b, c}	A	
	T _A = 70 °C		10 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	150		
Valanche Current	L = 0.1 mH	I _{AS}	25		
Avalanche Energy	L = 0.1 mm	E _{AS}	40	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C		15	A	
Sontindous Source-Drain Diode Current	T _A = 25 °C	I _S	2.9 ^{b, c}	~	
	T _C = 25 °C		28		
Aaximum Power Dissipation	T _C = 70 °C	Р	18	w	
	T _A = 25 °C	P _D	3.5 ^{b, c}	V V	
	T _A = 70 °C		2.2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	<u></u>	
Soldering Recommendations (Peak Tempera		260			

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient	t ≤ 10 s	R _{thJA}	29	36	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	3.6	4.5	0/11	

Notes:

a. Based on $T_C = 25 \text{ °C}$. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

SPECIFICATIONS $T_J = 25 \text{ °C}$, Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			33		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.2		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	15			Α	
Drain Courses On State Desistenced	P	V _{GS} = 10 V, I _D = 10 A	7				
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 7 \text{ A}$		9		mΩ	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 10 A		24		S	
Dynamic ^b						•	
Input Capacitance	C _{iss}			1700			
Output Capacitance	C _{oss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz		200		pF	
Reverse Transfer Capacitance	C _{rss}			150			
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$		33		nC	
Total Gate Charge	٩g			18			
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 10 A		7.3			
Gate-Drain Charge	Q _{gd}			6.2			
Gate Resistance	R _g	f = 1 MHz	0.2	0.8	1.6	Ω	
Turn-On Delay Time	t _{d(on)}			15	30		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		12	24	- - - ns	
Turn-Off Delay Time	t _{d(off)}	${ m I}_{ m D}\cong$ 10 A, ${ m V}_{ m GEN}$ = 4.5 V, ${ m R}_{ m g}$ = 1 Ω		13	26		
Fall Time	t _f			10	20		
Turn-On Delay Time	t _{d(on)}			9	18	110	
Rise Time	t _r	V_{DD} = 15 V, R _L = 1.5 Ω		9	18	_	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		14	28		
Fall Time	t _f			8	16		
Drain-Source Body Diode Characteristi	cs		r	1	r		
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			16	A	
Pulse Diode Forward Current	I _{SM}				32		
Body Diode Voltage	V _{SD}	I _S = 3 A, V _{GS} = 0 V		0.78	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			17	34	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _{.1} = 25 °C		9.5	19	nC	
Reverse Recovery Fall Time	t _a			10		– ns	
Reverse Recovery Rise Time	t _b			7			

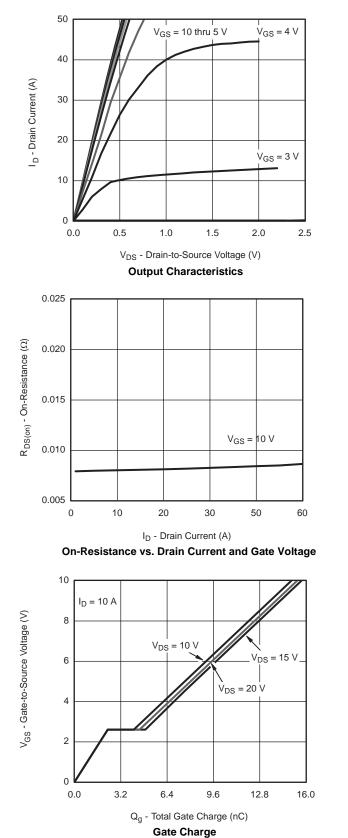
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

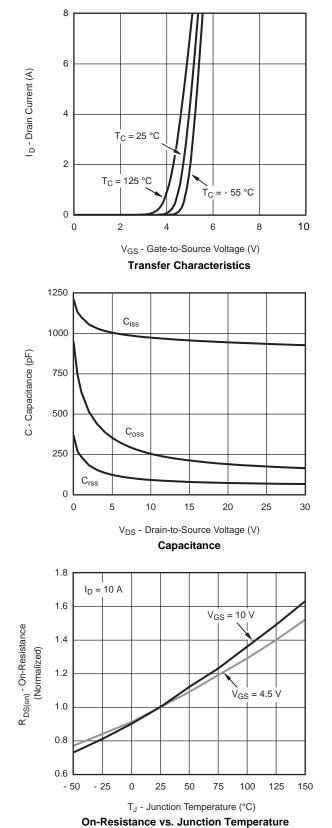
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



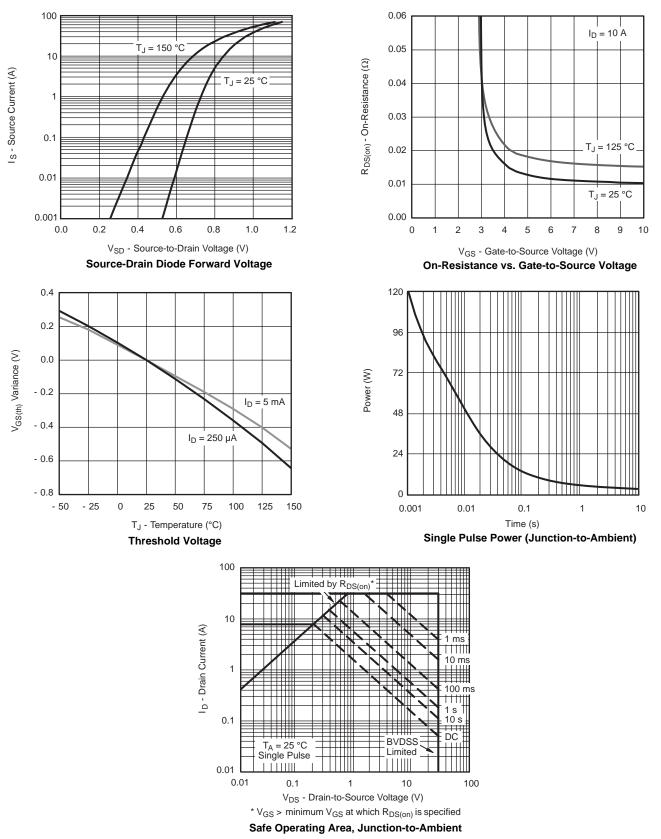




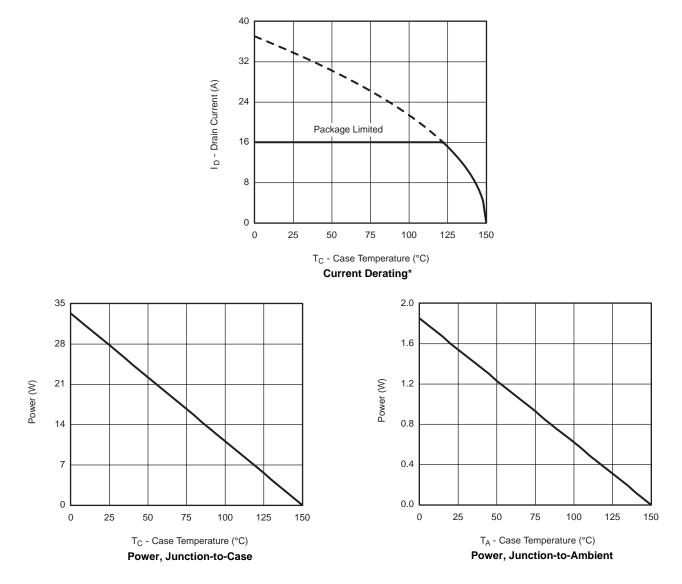


服务热线:400-655-8788



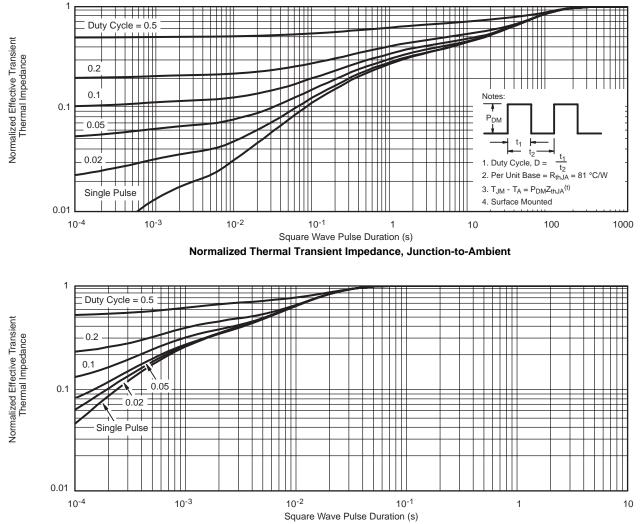






* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

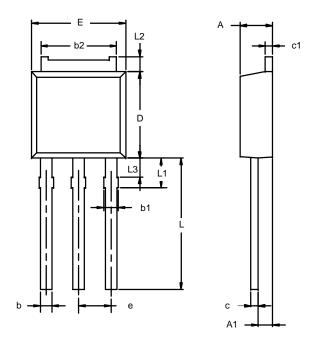




Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					



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